



Electrically Conductive Adhesives

Lecture II: ICAs

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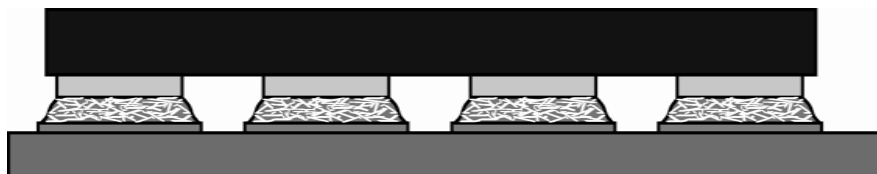
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Electrically Conductive Adhesives

C. Isotropic Conductive Adhesives

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|-----------------|------------------|
| 1. Introduction | 5. Mechanical |
| 2. Structure | 6. Thermal |
| 3. Curing | 7. Reliability |
| 4. Electrical | 8. Miscellaneous |



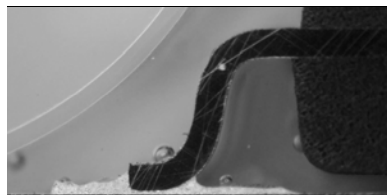
1. Introduction to ICAs

- 1.1 Applications
- 1.2 Processing
- 1.3 Structure & Percolation
- 1.4 Properties
- 1.5 Problem History

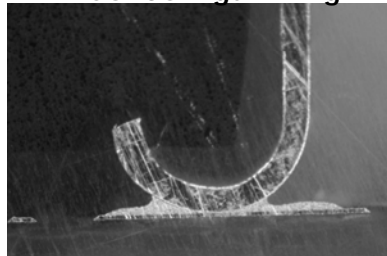
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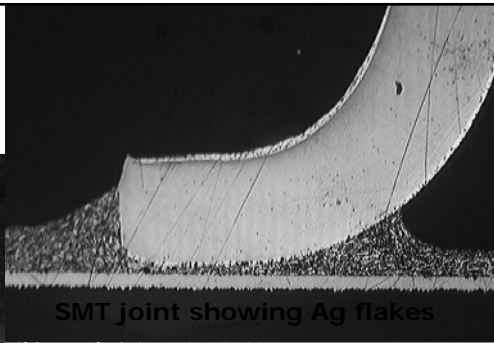
1.1 ICA applications



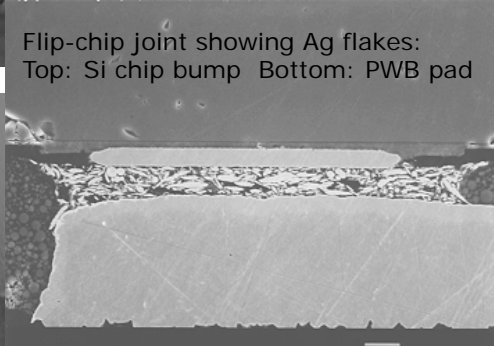
SO20GT: gull-wing



PLCC68T: J-lead



SMT joint showing Ag flakes



Flip-chip joint showing Ag flakes:
Top: Si chip bump Bottom: PWB pad

0002 15KV X800 10µm WD17